

## Electronic Patent Application Fee Transmittal

Application Number:	10537509			
Filing Date:	30-Nov-2005			
Title of Invention:	Method for cutting semiconductor substrate			
First Named Inventor/Applicant Name:	Fumitsugu Fukuyo			
Filer:	John G. Smith/Tina Fluharty			
Attorney Docket Number:	46884-5388 (211285)			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Submission- Information Disclosure Stmt	1806	1	180	180
<b>Total in USD (\$)</b>				<b>180</b>